

NOTES:

1. MATERIAL:
  - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0;
  - 1.2 CONTACT: COPPER ALLOY
2. FINISH:
  - 2.1 CONTACT:
    - N: 50~100u" MATTE TIN PLATING OVERALL
    - 50u" MIN. NICKEL UNDERPLATING OVERALL
3. SPEC. PLS. REFER TO PS-51281-XXXXX-XXX
4. PART NUMBER

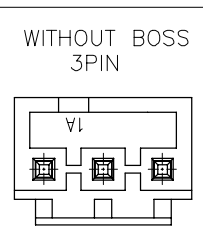
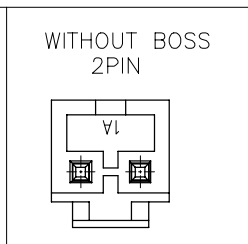
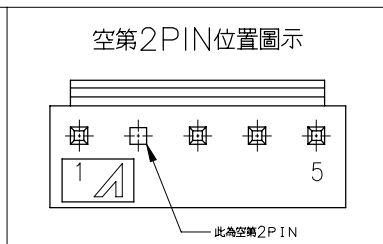
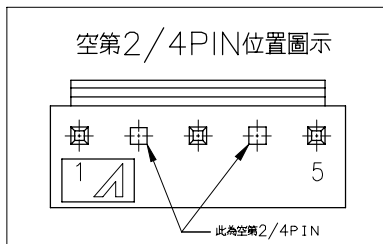
51281-XXX X X-XXX

XXX	HOUSING MATERIAL	HALOGEN FREE	DIM C	VOID CKT
001	PA66 PLASTIC	HF	3.70	NA
020	PA66 PLASTIC	HF	3.70	空第 2PIN
024	PA66 PLASTIC	HF	3.70	空第 2/4PIN

NO OF CKT  
PACKING  
3:BAG

PLATING  
N: MATTE TIN PLATING OVERALL

CKT	Dim A	Dim B
2	7.86	3.96
3	11.82	7.92
4	15.78	11.88
5	19.74	15.84



QUALITY SYMBOLS

MAJOR Ⓢ

CRITICAL Ⓢ

GENERAL TOLERANCES (UNLESS SPECIFIED)

X. ±0.5

X ±0.25

.XX ±0.15

.XXX ±0.1

ANGLES ±2°

DRAWN BY	DATE
Huang,Shun Sen	20/06/06
CHECKED BY	DATE
Lu,ling Quan	20/06/06
APPROVED BY	DATE
hsieh,fu yu	20/06/06

		TITLE	
		3.96mm WTB WAFER CONN. T/H S/T TYPE	
UNITS		SIZE	RFG NO.
mm		A4	N/A
SCALE	SHEET NO.	REV	DWG NO.
3:1	- OF -	C	51281-XXXXX-XXX